



* SURFACE - AIR 0 MIL
L1: TOP CONDUCTOR - COPPER 2.7 MIL
* DIELECTRIC - FR-4 9.4 MIL
L2: IN1 CONDUCTOR - COPPER 2.7 MIL

* DIELECTRIC - FR-4 35 MIL

L3: IN2 CONDUCTOR - COPPER 2.7 MIL
* DIELECTRIC - FR-4 9.4 MIL

L4: BOTTOM CONDUCTOR - COPPER 2.7 MIL
* SURFACE - AIR 0 MIL

DESIGN CROSS SECTION CHART
TOTAL THICKNESS 64.6 MIL

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

- BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
- THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
- MATERIAL:
 - FR408 PER IPC 4101B/24 /26, OR /28.
 - SIGNAL LAYERS TO BE 2 OZ. COPPER.
 - PLANE LAYERS TO BE 2 OZ. COPPER.
 - OVERALL THICKNESS TO BE 0.062" +/- 10%
- LEGEND:
 - WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
- SOLDERMASK:
 - APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR MATTE BLUE, BOTH SIDES.
- PLATING FINISH:
 - HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
 - ~~IMMERSE SOLDER PLATING.~~
- PROCESS ALLOWANCES:
 - MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH
 - HOLE DIMENSIONS APPLY AFTER PLATING.
 - ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
 - LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003"
 - CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
 - REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
 - CUT OUTSIDE OF 0.001" BOARD OUTLINE.

